



Product / Process Change Notice

No.: Z200-PCN-DM201801-01-A

Date: 01/17/2018

Change Title : 2Gb (256Mbx8 and 128Mbx16) DDR3/DDR3L technology migration from 46nm to 38nm for Industrial grade

Change Classification: Major Minor with customer information

Change item : Design Raw Material Wafer FAB Assembly Testing Packing Others

Affected Product(s) :

W632GU6KB11I ,W632GG6KB15I ,W632GG8KB15I ,W632GU8KB12I ,W632GG6KB12J ,W632GG8KB12I ,
W632GU8KB15I ,W632GU6KB15I ,W632GG6KB11I ,W632GG6KB12I ,W632GG6KB15J ,W632GU6KB12I ,
W632GU6KB12J

Description of Change(s)

Technology migration (46nm to 38nm) for 2Gb DDR3/DDR3L Industrial grade.

Reason for Change(s) :

According to Winbond product roadmap, launch new 2Gb DDR3/DDR3L Industrial grade with 38nm technology.

Impact of Change(s) : (positive & negative)

Form : No Change

Fit : Change (Package size change from 9x13x1.2(46nm) to 7.5x13x1.0(38nm).

Package size change from 8x10.5x1.2(46nm) to 8x10.5x1.0(38nm),

but the ball arrays are identical and pin to pin fully compatible, refer to attachment I)

Function : No Concern (The function is fully compatible between 46nm and 38nm, refer to attachment II)

Reliability : No Concern (The reliability test pass, refer to attachment III)

Hazardous Substances: No Concern (Please refer to attachment IV)

Qualification Plan/ Results :

Base on Winbond Reliability report, the Industrial grade meets Winbond criteria and no quality concern (refer to Attachment III in detail).

Implementation Plan :

Industrial grade product launch date of the 38nm 256Mb x8 and 128Mb x16 2Gb DDR3/ DDR3L: Dec 18, 2017.

Proposed ship date of the 38nm 256Mb x8 and 128Mb x16 2Gb DDR3/DDR3L Industrial grade: Jan 25, 2018.

The follow-up disposition of 46nm 256Mb x8 and 128Mb x16 2Gb DDR3/DDR3L Industrial grade:

1) The date of Last-buy orders for the 46nm 256Mb x8 and 128Mb x16 2Gb DDR3/DDR3L Industrial grade: Jan 25, 2019.

2) The last shipment date of the 46nm 256Mb x8 and 128Mb x16 2Gb DDR3/DDR3L Industrial grade: Jan 25, 2020.

Date Code: _____ onward Lot No: 665300100ZJ onward Proposed first ship date: _____.

Originator: (QA) Hyhuang	Approval: (QA Dept. Manager) YH Cheng	Approval: (QRA Director) Geron Chen
Contact for Questions & Concerns	Name: <u>Betty Huang</u> TEL: <u>886-3-5678168</u> (ext.86549) FAX: <u>886-3-5796124</u> Address : <u># 539, Sec. 2, Wenxing Rd., Jhubei City, Hsinchu County 302, Taiwan</u> E-mail: <u>Hyhuang8@winbond.com</u>	

Customer Comments:

Note: Please sign this notice, and return to Winbond contact within 30 days. If no response is received within 30 days, this Change Request will be assumed to meet your approval.

Major change: <input type="checkbox"/> Approval <input type="checkbox"/> Disapproval <input type="checkbox"/> Conditional Approval : _____
Minor change with customer information: <input type="checkbox"/> Recognition
Date: _____
Dept. name: _____
Person in charge: _____



The comparison table of part no between 46nm and 38nm

Product	46nm Part No	38nm Part No
DDR3 128Mb x16	W632GG6KB	W632GG6MB
DDR3 256Mb x8	W632GG8KB	W632GG8MB
DDR3L 128Mb x16	W632GU6KB	W632GU6MB
DDR3L 256Mb x8	W632GU8KB	W632GU8MB